

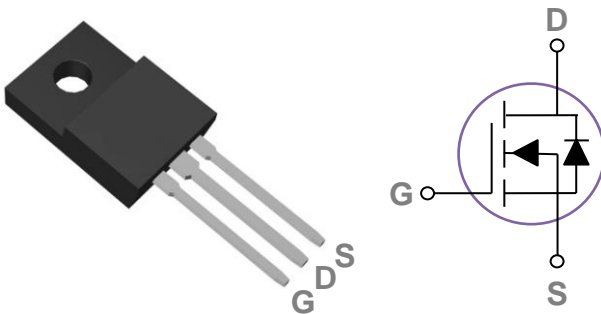
**General Description**

These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
800V	275mΩ	17A

**Features**

- 800V, 17A, R<sub>DS(ON)</sub> = 275mΩ @ V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

**TO220F Pin Configuration**

**Applications**

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

**Absolute Maximum Ratings** T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	800	V
V <sub>GS</sub>	Gate-Source Voltage	±30	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	17	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	10.8	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	68	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	281	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	7.5	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	60	W
	Power Dissipation – Derate above 25°C	0.48	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	2.1	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	800	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=800V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=640V, V_{GS}=0V, T_J=100^\circ C$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	100	nA

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=11A$	---	220	275	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V

**Dynamic and switching Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=640V, V_{GS}=10V, I_D=17A$	---	57.5	86	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	6.6	10	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	24	36	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DS}=400V, V_{GS}=10V, R_G=25\Omega, I_D=17A$	---	32	50	ns
$T_r$	Rise Time <sup>3,4</sup>		---	56.5	85	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	160	240	
$T_f$	Fall Time <sup>3,4</sup>		---	49	75	
$C_{iss}$	Input Capacitance	$V_{DS}=640V, V_{GS}=0V, F=1MHz$	---	1800	2700	pF
$C_{oss}$	Output Capacitance		---	40	60	
$C_{rss}$	Reverse Transfer Capacitance		---	7	11	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	2.1	---	$\Omega$

**Guaranteed Avalanche Energy**

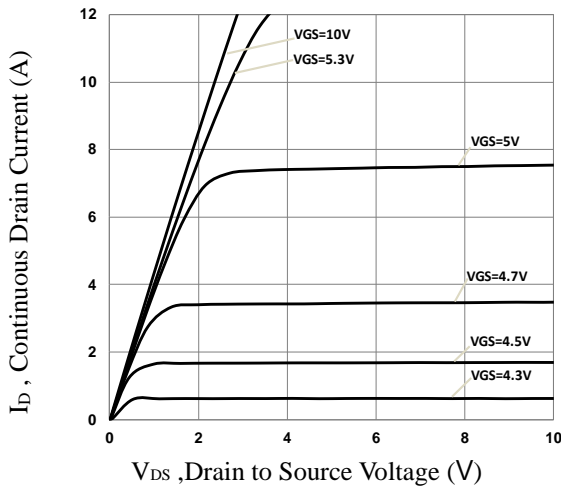
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=100V, L=10mH, I_{AS}=3.5A$	61	---	---	mJ

**Drain-Source Diode Characteristics and Maximum Ratings**

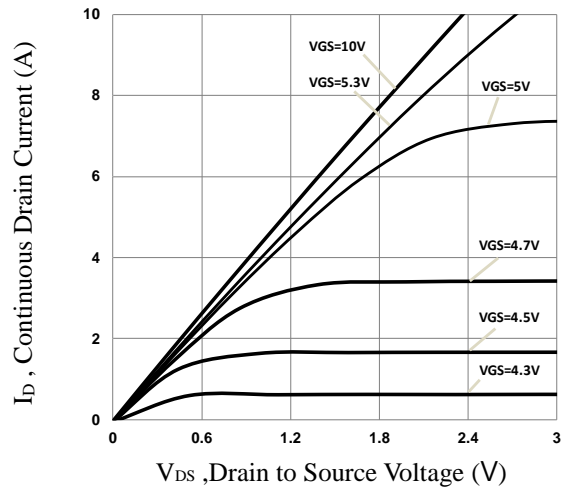
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	17	A
$I_{SM}$	Pulsed Source Current		---	---	34	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=10A, T_J=25^\circ C$	---	---	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_R=400V, I_S=17A$	---	495	---	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s, T_J=25^\circ C$	---	8920	---	nC

Note :

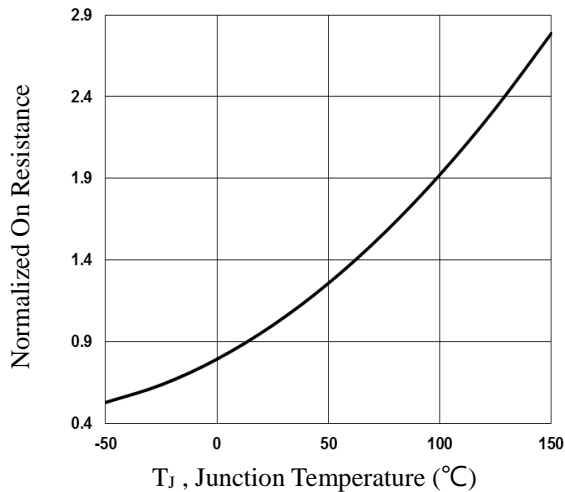
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=100V, V_{GS}=10V, L=10mH, I_{AS}=7.5A, R_G=25\Omega, \text{Starting } T_J=25^\circ C$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



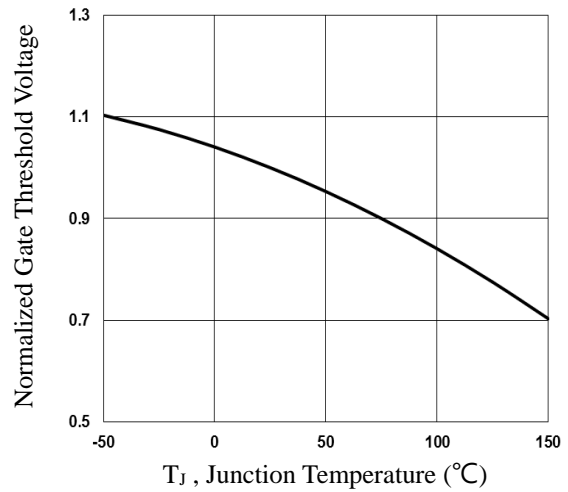
**Fig.1 Typical Output Characteristics**



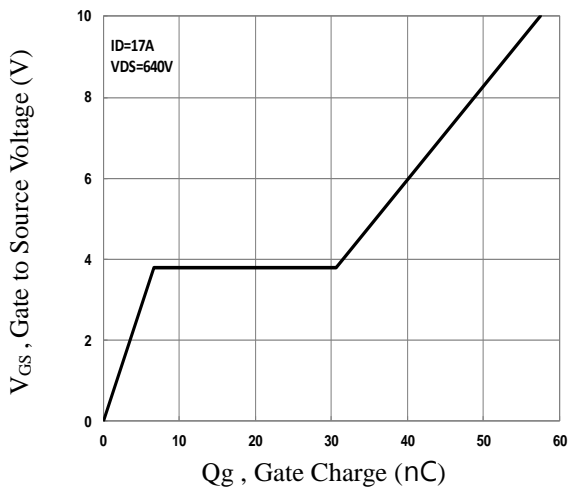
**Fig.2 Typical Output Characteristics**



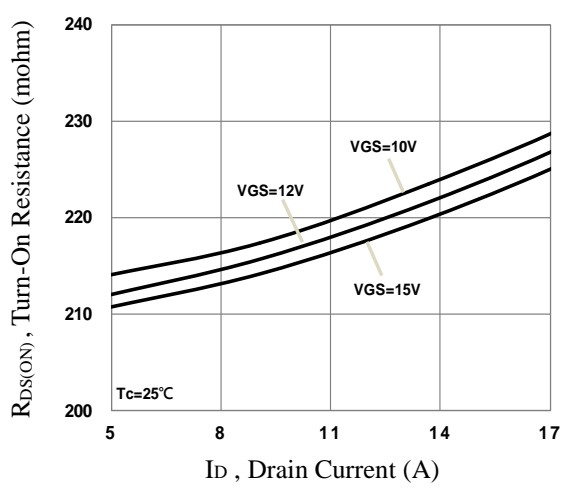
**Fig.3 Normalized  $R_{DS(on)}$  vs.  $T_J$**



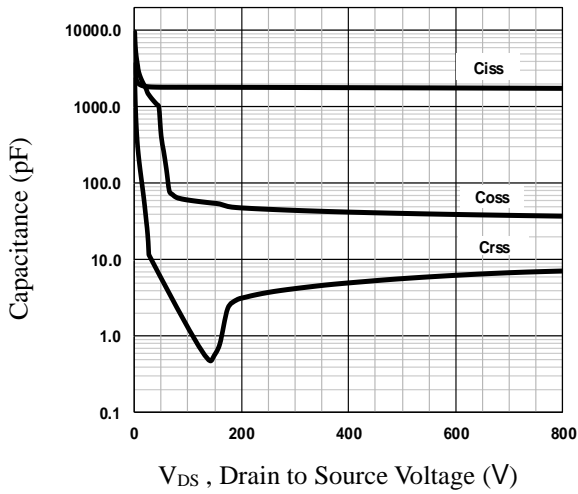
**Fig.4 Normalized  $V_{th}$  vs.  $T_J$**



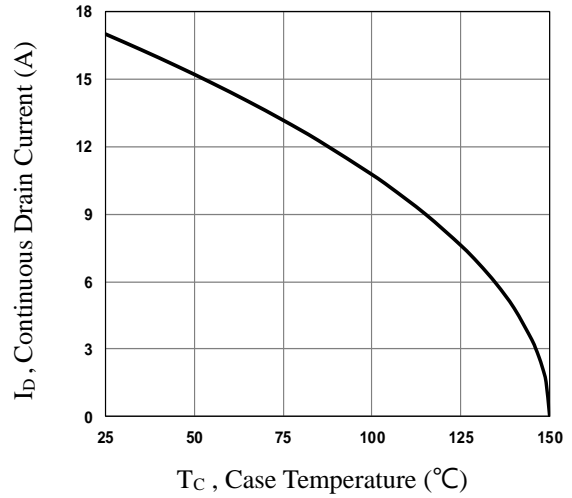
**Fig.5 Gate Charge Characteristics**



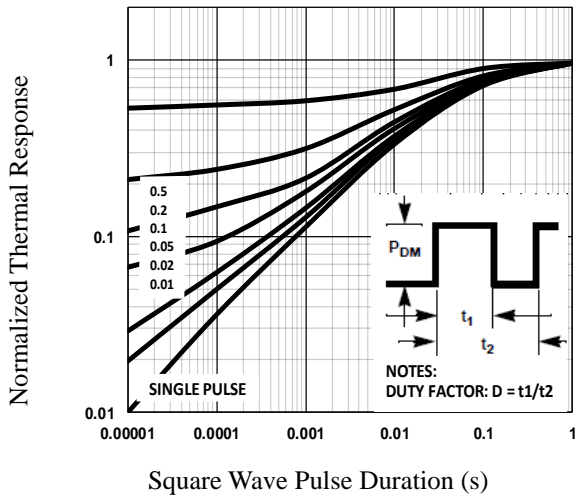
**Fig.6 Turn-On Resistance vs.  $I_D$**



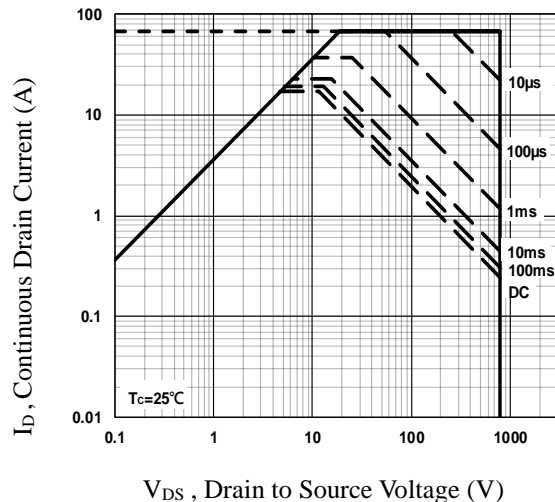
**Fig.7 Capacitance Characteristics**



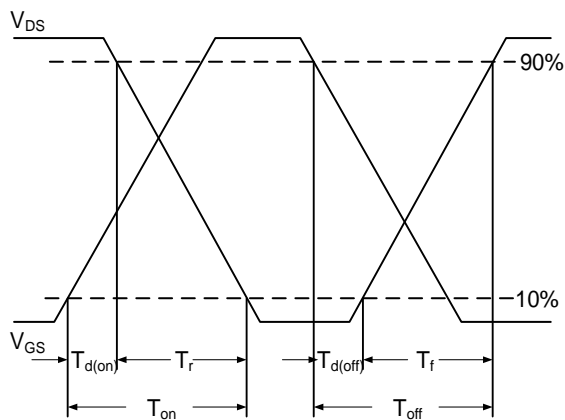
**Fig.8 Continuous Drain Current vs.  $T_C$**



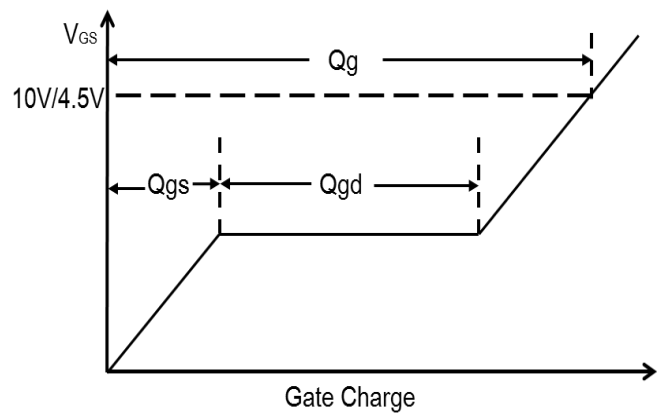
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**

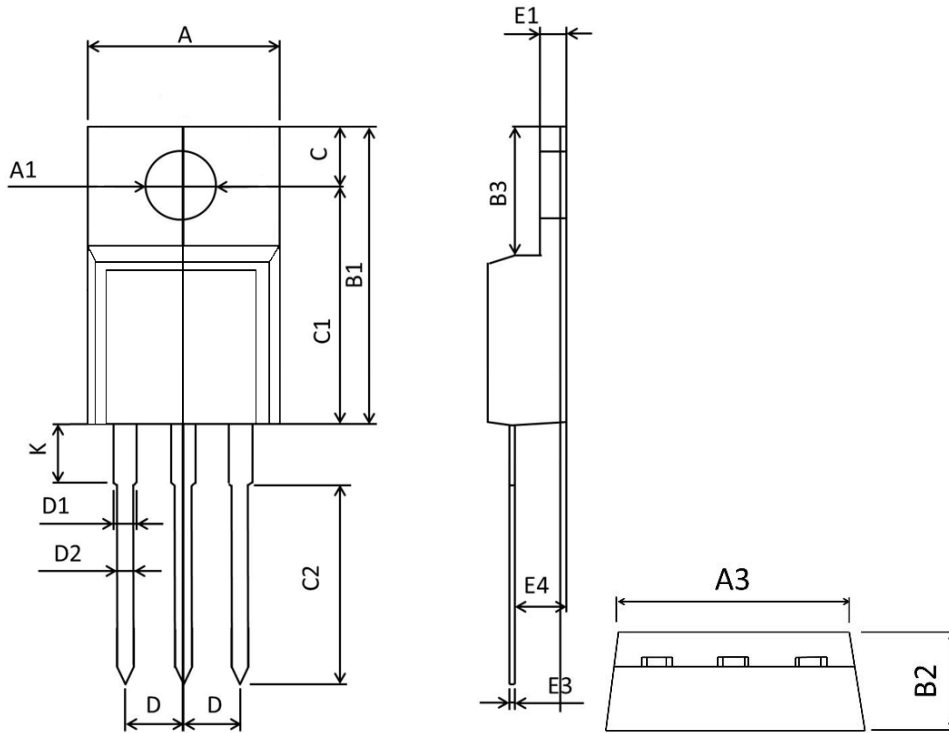


**Fig.11 Switching Time Waveform**



**Fig.12 Gate Charge Waveform**

**TO220F PACKAGE INFORMATION**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.860	10.460	0.389	0.411
A1	3.100	3.500	0.122	0.138
B1	15.450	16.300	0.608	0.642
B2	4.400	5.000	0.173	0.197
B3	6.280	7.100	0.247	0.280
C	3.100	3.500	0.122	0.138
C1	12.270	12.870	0.483	0.507
C2	9.600	10.520	0.378	0.414
D	2.540BSC		0.1BSC	
D1	1.070	1.470	0.042	0.058
D2	0.600	1.000	0.024	0.039
K	2.800	3.500	0.110	0.138
E1	2.340	2.740	0.092	0.108
E3	0.350	0.650	0.014	0.026
E4	2.460	2.960	0.097	0.117